

LASER DEVICE

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Inventor(s): OGAWA TAKESHI
Applicant(s): NEC CORP
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Abstract

PURPOSE:To facilitate the mounting and bonding of a laser chip so as to improve a laser device in productivity and manufacturing yield by a method wherein the laser chip mounted on the upside of a mount and a photodetecting element are provided, and the photodetecting element is installed making its light detecting face tilted by a specified angle with light emitted from the laser chip.

CONSTITUTION:A laser chip 1 is mounted on the upside of a mount 5 formed on a stem 4 of a package. A monitoring photodetective element 3 provided with a reflective film 6 whose reflectivity is 80-95% formed on its surface is installed making an angle of 45 degrees with light rays outputted from the laser chip 1. Light rays outputted from the laser chip 1 is reflected from the surface of the monitoring photodetecting element 3 and 80-95% of it is taken outside as a primary beam 2 through a window. The rest, 5-10% of the light, is made to be incident on a monitoring photodetective element 3 as monitored light rays.

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